

02-14-02

A

Docket No. 5018/ISM/CORE MCVD

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Box Patent Application
 Commissioner of Patents and Trademarks
 Washington, D.C. 20231

Re: Inventor(s): Avi TEPMAN and Lawrence Chung-lai LEI
 Title: VARIABLE FLOW DEPOSITION APPARATUS AND METHOD IN SEMICONDUCTOR SUBSTRATE PROCESSING

1002 U.S. PTO
 10/074854
 02/11/02

Transmitted herewith is the patent application identified above, including:

- ☒ Specification, claims and abstract, totaling 29 pages.
- ☒ Drawings totaling 4 pages, Formal Informal.
- ☒ Executed Declaration and Power of Attorney.
- ☒ Assignment of the invention to **Applied Materials, Inc.**
- ☒ Assignment Recordation Cover Sheet
- ☐ Information Disclosure Statement (37 CFR 1.98)

FEE CALCULATION					
Fee Items	Claims Filed	Included With Basic Fee	Extra Claims	Fee Rate	Total
Total Claims	51	-20=	31	X\$18.00	\$ 558.00
Independent Claims	6	-3=	3	X\$84.00	\$ 252.00
Basic Filing Fee				\$740.00	\$ 740.00
TOTAL FEES					\$1550.00

- ☒ The Commissioner is hereby authorized to charge \$1550.00 to Deposit Account No. 50-1074.
- ☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 50-1074. A duplicate copy of this transmittal is enclosed.
- ☒ Please address all future correspondence to:
- PATENT COUNSEL**
APPLIED MATERIALS, INC.
Legal Affairs Department
P.O. BOX 450A
Santa Clara, CA. 95052

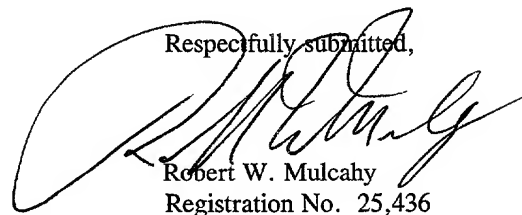
I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231.

Express Mail Receipt No. E049824328US

Date of Deposit 2-11-02

Signature Ben Mulcahy

Respectfully submitted,


 Robert W. Mulcahy
 Registration No. 25,436